

REMARKS/ARGUMENTS

Favorable reconsideration of this application as presently amended and in light of the following discussion is respectfully requested.

Claims 1-10, 15 and 73-80 are presently active, Claims 11-14 and 16-72 having been withdrawn from further consideration as directed to non-elected inventions, Claims 1, 6-9 and 15 having been amended, and Claims 73-80 having been newly added. No new matter has been added.

In the outstanding Office Action, Claims 1-10 were rejected under the judicially created doctrine of obviousness-type double patenting over Claims 1-10 in U.S. Pat. No. 6,724,638. Claim 1-10 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Sunahara (U.S. Pat. No. 6,153,290) in view of Ehman et al (U.S. Pat. No. 6,021,050), and further in view of Lauffer et al (U.S. Pat. No. 5,029,253). Claim 15 was rejected under 35 U.S.C. § 103(a) as being unpatentable over Sunahara in view of Ehman et al, and further in view of Gorczyca et al (U.S. Pat. No. 5,161,093).

Regarding the double-patenting rejection, Applicants respectfully submit that the outstanding ground for rejection has been overcome, because in Applicant's view, amended independent Claim 1 and its dependent Claims 2-10 patentably distinguish over Claims 1-10 in U.S. Pat. No. 6,724,638 as discussed below.

Amended Claim 1 recites "a conductive pad is formed on the first resin substrate and connected to an electrode of the capacitor" and "a via hole, through which the conductive pad is connected to the conductive circuit on the core substrate, is formed in the first resin substrate." Claims 1-10 in U.S. Pat. No. 6,724,638 fail to teach or suggest these features, and therefore fail to meet all of the limitations of Claim 1 of the instant application.

Thus, Applicants respectfully submit that the amended independent Claim 1 and its dependent Claims 2-10 patentably distinguish over Claims 1-10 in U.S. Pat. No. 6,724,638, and therefore the double-patenting rejection has been overcome.

Regarding the 35 U.S.C. § 103(a) rejection of Claims 1-10, Applicants respectfully submit that the outstanding ground for rejection has been overcome, because in Applicants' view, amended independent Claim 1 patentably distinguishes over the cited references, as discussed below.

Amended Claim 1 recites "a printed circuit board constituted by alternately laminating interlayer resin insulating layers and conductive circuits on a core substrate", "a conductive pad is formed on the first resin substrate and connected to an electrode of the capacitor" and "a via hole, through which the conductive pad is connected to the conductive circuit on the core substrate, is formed in the first resin substrate." By connecting the electrode of the capacitor in the core substrate to the conductive circuit on the core substrate through a via hole, a printed circuit board recited in Claim 1 enables to shorten the distance between the conductive circuit on the core substrate and the capacitor in the core substrate so as to reduce the loop inductance of the printed circuit board.

Instead, the outstanding Office Action states that Sunahara discloses a printed circuit board as shown in figures 1-4 constituted by alternately laminating interlayer insulating layers (9) and conductive circuits (13-18) on a core substrate (1). However, Sunahara does not disclose a printed circuit board constituted by alternately laminating interlayer insulating layers and conductive circuits on a core substrate because the multi-layer ceramic substrate (1) includes the laminate (9)¹, and therefore, both the multi-layer ceramic substrate (1) and the laminate (9) in Sunahara correspond to a core substrate recited in Claim 1. Therefore, Sunahara also fails to teach or suggest "a conductive pad is formed on the first resin substrate

¹ Column 5, lines 29-34.

and connected to an electrode of the capacitor” and “a via hole, through which the conductive pad is connected to the conductive circuit on the core substrate, is formed in the first resin substrate.”

Additionally, neither Ehman et al, nor Lauffer et al teach or suggest “a conductive pad is formed on the first resin substrate and connected to an electrode of the capacitor” and “a via hole, through which the conductive pad is connected to the conductive circuit on the core substrate, is formed in the first resin substrate” recited in Claim 1.

Thus, Applicants respectfully submit that the amended independent Claim 1 patentably distinguishes over the cited references and is believed to be allowable. Further, dependent Claims 2-10 which depend from Claim 1 are also believed to be allowable.

The substantially same arguments apply to the 35 U.S.C. § 103(a) rejection of Claim 15. Additionally, Gorczyca et al also fails to teach or suggest “a conductive pad is formed on the first resin substrate and connected to an electrode of the capacitor” and “a via hole, through which the conductive pad is connected to the conductive circuit on the core substrate, is formed in the first resin substrate” recited in Claim 15.

Thus, Applicants respectfully submit that the amended Claim 15 patentably distinguishes over the cited references and is believed to be allowable.

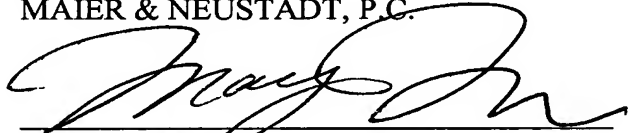
Finally, newly added Claims 73 and 74 are dependent from the independent Claims 1 and 15 respectively and therefore are believed to be allowable. Further, newly added Claims 75-80 include the features which are not taught or suggested by the cited references and therefore are also believed to be allowable.

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Consequently, in view of the present amendment and in light of the above discussions, the outstanding grounds for rejection are believed to have been overcome. The application as amended herewith is believed to be in condition for formal allowance. An early and favorable action to that effect is respectfully requested.

Respectfully submitted,

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